

ABSTRACT

A plastic package includes a plurality of terminal members each having an outer terminal, an inner terminal, and a connecting part connecting the outer and the inner terminal; a semiconductor device provided with terminal pads connected to the inner terminals with bond wires; and a resin molding sealing the terminal members, the semiconductor device and the bond wires therein. The inner terminals of the terminal members are thinner than the outer terminals and have contact surfaces. The upper, the lower and the outer side surfaces of the outer terminals, and the lower surfaces of the semiconductor device are exposed outside. The inner terminals, the bond wires, the semiconductor device and the resin molding are included in the thickness of the outer terminals.